

WAFER DICING DEVICE AND METHOD

ABSTRACT

Methods and devices for cutting workpieces, which include a laser adapted to at least partially cut a workpiece, are described. The workpiece is a
5 wafer having a plurality dies each with an integrated circuit. A mechanical cutter follows the laser and engages the workpiece. An embodiment of the mechanical cutter includes a cutting blade adapted to complete a cut through a workpiece. A method includes a two-pass cutting procedure. The first pass is made by a laser, which scribes the workpiece. The second pass is made by the
10 mechanical cutter. In an embodiment, the mechanical cutter follows the scribe created by the laser. In an embodiment, the workpiece is supported by a table. The workpiece moves relative to the laser and the mechanical cutter.

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